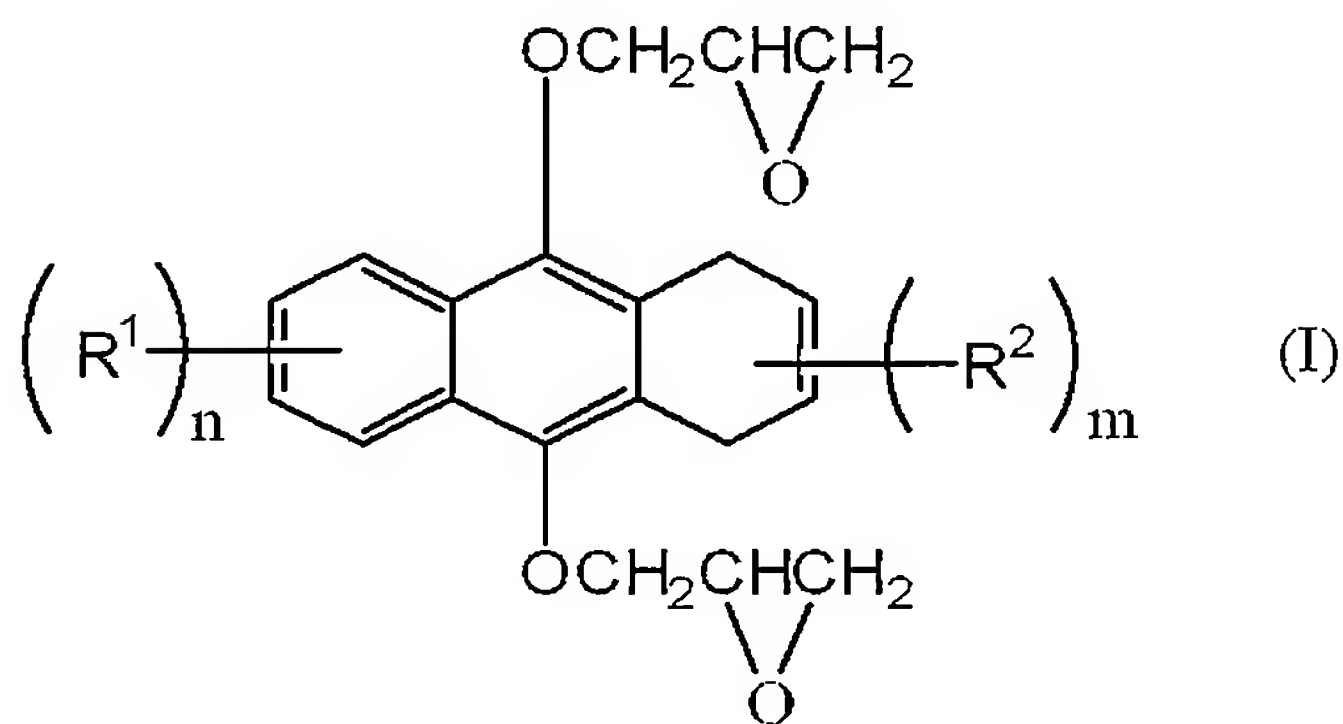


IN THE CLAIMS:

These claims will replace all prior versions of claims in the present application.

1. (Original) A sealant epoxy-resin molding material, comprising an epoxy resin (A) and a hardening agent (B), wherein the epoxy resin (A) contains a compound represented by the following General Formula (I):

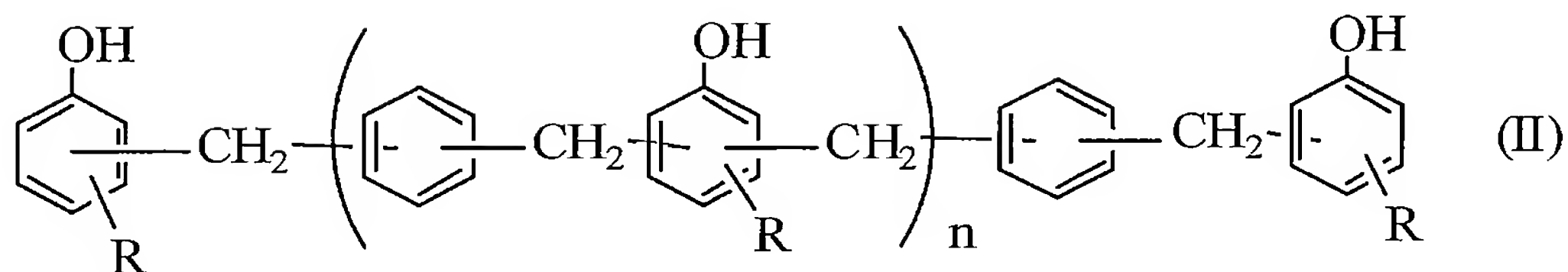
[Formula 1]



(in General Formula (I), R¹ represents a group selected from substituted or unsubstituted hydrocarbon groups having 1 to 12 carbon atoms and substituted or unsubstituted alkoxy groups having 1 to 12 carbon atoms, and the groups R¹ may be the same as or different from each other; n is an integer of 0 to 4; R² represents a groups selected from substituted or unsubstituted hydrocarbon groups having 1 to 12 carbon atoms and substituted or unsubstituted alkoxy groups having 1 to 12 carbon atoms and the groups R² may be the same as or different from each other; and m is an integer of 0 to 6).

2. (Original) The sealant epoxy-resin molding material according to Claim 1, wherein the hardening agent (B) contains a compound represented by the following General Formula (II):

[Formula 2]



(wherein, R represents a group selected from a hydrogen atom and substituted or unsubstituted monovalent hydrocarbon groups having 1 to 10 carbon atoms; and n is an integer of 0 to 10).

3. (Currently Amended) The sealant epoxy-resin molding material according to Claim 1-~~or 2~~, further comprising a hardening accelerator (C).

4. (Original) The sealant epoxy-resin molding material according to Claim 3, wherein the hardening accelerator (C) is triphenylphosphine.

5. (Original) The sealant epoxy-resin molding material according to Claim 3, wherein the hardening accelerator (C) is an adduct of a tertiary phosphine compound and a quinone compound.

6. (Currently Amended) The sealant epoxy-resin molding material according to ~~any one of Claims 1 to 5~~ Claim 1, further comprising an inorganic filler (D).

7. (Original) The sealant epoxy-resin molding material according to Claim 6, wherein the content of the inorganic filler (D) is 60 to 95 wt % with respect to the sealant epoxy-resin molding material.

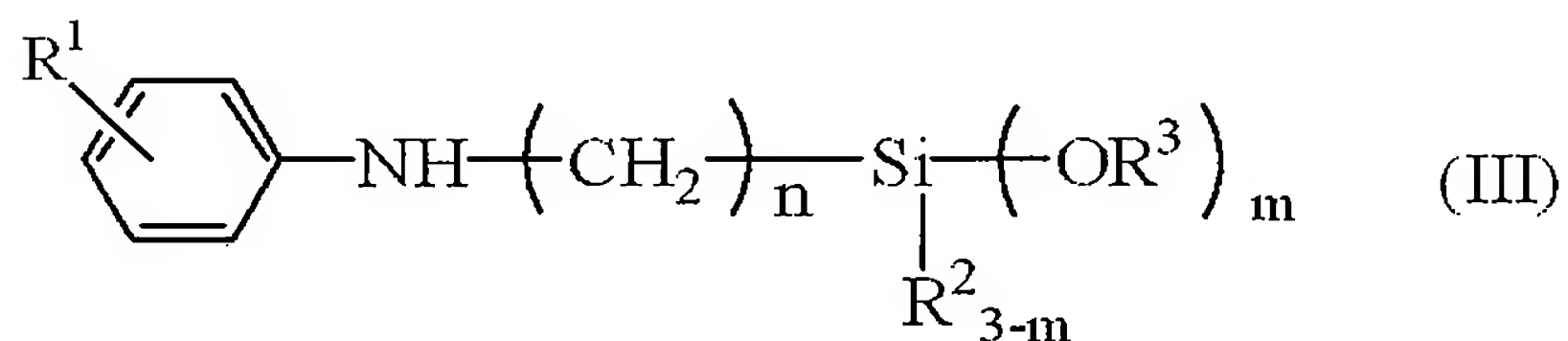
8. (Currently Amended) The sealant epoxy-resin molding material according to Claim 6-~~or 7~~, wherein the content of the inorganic filler (D) is 70 to 90 wt % with respect to the sealant epoxy-resin molding material.

9. (Currently Amended) The sealant epoxy-resin molding material according to ~~any one of Claims 1 to 8~~Claim 1, further comprising a coupling agent (E).

10. (Original) The sealant epoxy-resin molding material according to Claim 9, wherein the coupling agent (E) contains a secondary amino group-containing silane-coupling agent.

11. (Original) The sealant epoxy-resin molding material according to Claim 10, wherein the secondary amino group-containing silane-coupling agent contains a compound represented by the following General Formula (III):

[Formula 3]

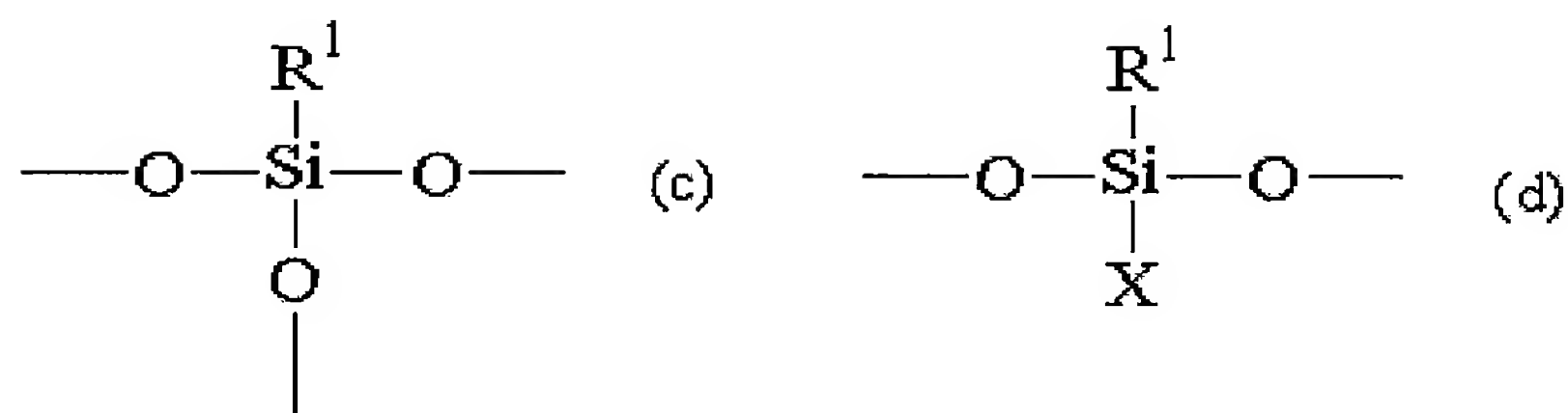


(wherein, R¹ represents a group selected from a hydrogen atom, alkyl groups having 1 to 6 carbon atoms, and alkoxy group having 1 to 2 carbon atoms; R² represents a group selected from alkyl groups having 1 to 6 carbon atoms and a phenyl group; R³ represents a methyl or ethyl group; n is an integer of 1 to 6; and m is an integer of 1 to 3).

12. (Currently Amended) The sealant epoxy-resin molding material according to ~~any one of Claims 1 to 11~~Claim 1, wherein the epoxy resin (A) and the hardening agent (B) are melt-mixed previously.

13. (Currently Amended) The sealant epoxy-resin molding material according to ~~any one of Claims 1 to 12~~Claim 1, further comprising a silicon-containing polymer (F) having the following bonds (c) and (d), a terminal selected from R¹, a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000.

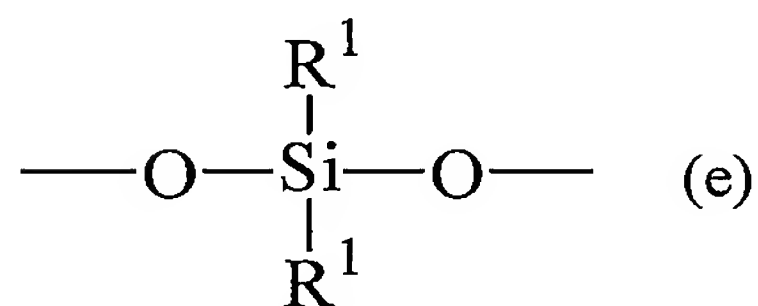
[Formula 4]



(wherein, R¹ represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms; the groups R¹ in the silicon-containing polymer may be the same as or different from each other; and X represents an epoxy group-containing monovalent organic group).

14. (Original) The sealant epoxy-resin molding material according to Claim 13, wherein the silicon-containing polymer (F) has the following bond (e) additionally:

[Formula 5]



(wherein, R¹ represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms; and the groups R¹ in the silicon-containing polymer may be the same as or different from each other).

15. (Currently Amended) The sealant epoxy-resin molding material according to Claim 13-~~or 14~~, wherein the softening temperature of the silicon-containing polymer (F) is 40°C or higher and 120°C or lower.

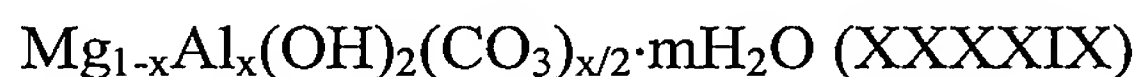
16. (Currently Amended) The sealant epoxy-resin molding material according to ~~any one of Claims 13 to 15~~Claim 13, wherein R¹ in the silicon-containing polymer (F) is at least

one of a substituted or unsubstituted phenyl group and a substituted or unsubstituted methyl group.

17. (Currently Amended) The sealant epoxy-resin molding material according to ~~any one of Claims 13 to 16~~Claim 13, wherein the rate of substituted or unsubstituted phenyl groups having 1 to 12 carbon atoms in all groups R^1 in the silicon-containing polymer (F) is 60 to 100 mol %.

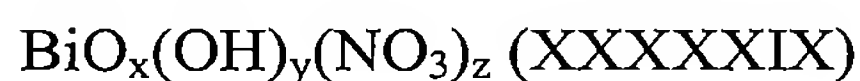
18. (Currently Amended) The sealant epoxy-resin molding material according to ~~any one of Claims 1 to 17~~Claim 1, further comprising at least one of a compound (G) represented by Compositional Formula (XXXXIX) and a compound (H) represented by the following Compositional Formula (XXXXXXIX):

(Formula 6)



($0 < X \leq 0.5$; and m is a positive number), and

(Formula 7)



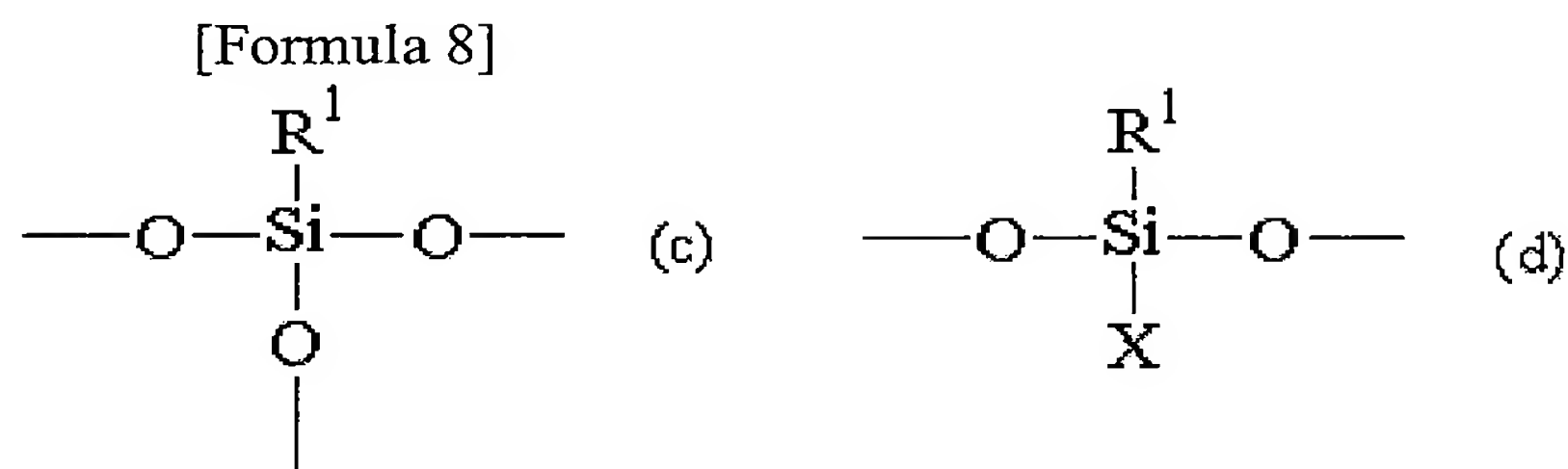
($0.9 \leq x \leq 1.1$, $0.6 \leq y \leq 0.8$, and $0.2 \leq z \leq 0.4$).

19. (Currently Amended) An electronic component device, comprising an element sealed with the sealant epoxy-resin molding material according to ~~any one of Claims 1 to 18~~Claim 13.

20. (NEW) The sealant epoxy-resin molding material according to Claim 6, further comprising a coupling agent (E).

21. (NEW) The sealant epoxy-resin molding material according to Claim 20, further comprising a silicon-containing polymer (F) having the following bonds (c) and (d), a

terminal selected from R¹, a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000.



(wherein, R¹ represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms; the groups R¹ in the silicon-containing polymer may be the same as or different from each other; and X represents an epoxy group-containing monovalent organic group).

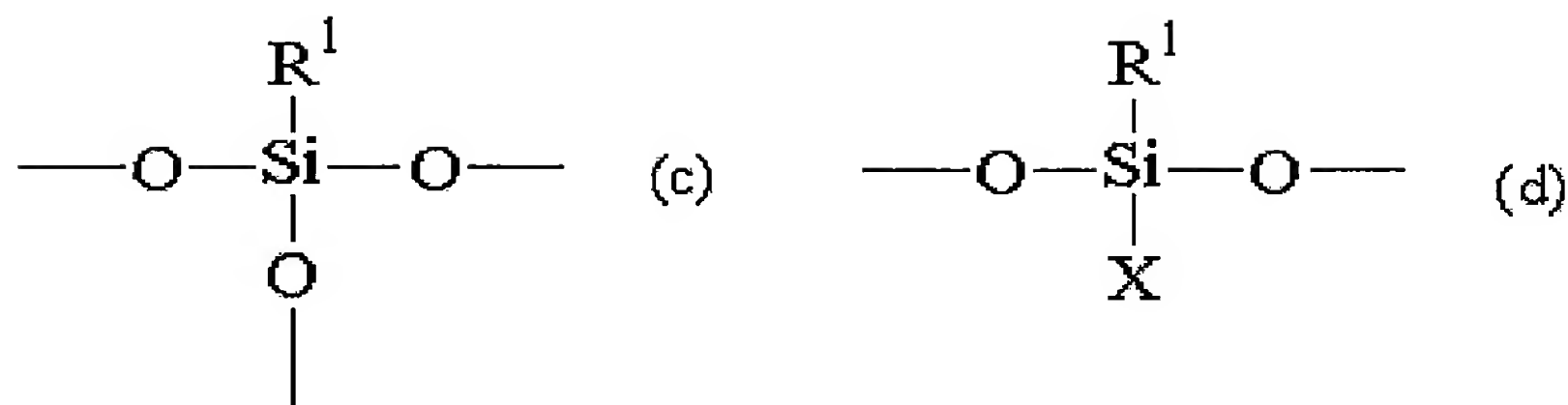
22. (NEW) The sealant epoxy-resin molding material according to Claim 3, further comprising an inorganic filler (D).

23. (NEW) The sealant epoxy-resin molding material according to Claim 3, further comprising a coupling agent (E).

24. (NEW) The sealant epoxy-resin molding material according to Claim 3, wherein the epoxy resin (A) and the hardening agent (B) are melt-mixed previously.

25. (NEW) The sealant epoxy-resin molding material according to Claim 3, further comprising a silicon-containing polymer (F) having the following bonds (c) and (d), a terminal selected from R¹, a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000.

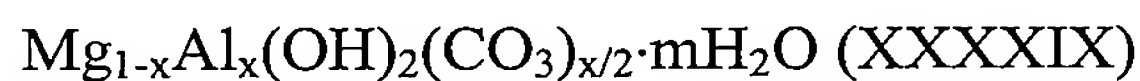
[Formula 4]



(wherein, R^1 represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms; the groups R^1 in the silicon-containing polymer may be the same as or different from each other; and X represents an epoxy group-containing monovalent organic group).

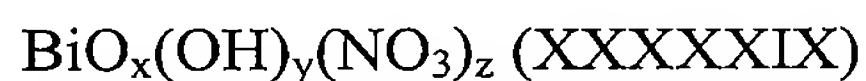
26. (NEW) The sealant epoxy-resin molding material according to Claim 3, further comprising at least one of a compound (G) represented by Compositional Formula (XXXXXIX) and a compound (H) represented by the following Compositional Formula (XXXXXXIX):

(Formula 6)



($0 < x \leq 0.5$; and m is a positive number), and

(Formula 7)



($0.9 \leq x \leq 1.1$, $0.6 \leq y \leq 0.8$, and $0.2 \leq z \leq 0.4$).